



Material Content Data Sheet



Sales Product Name		BSS159N H6327		Issued		29. August 2013		
MA#		MA000919342						
Package		PG-SOT23-3-5		Weight*		9.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.008	0.09		860	
	non noble metal	tin	7440-31-5	0.002	0.02		222	
	inorganic material	silicon	7440-21-3	0.091	0.97	1.08	9745	10827
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		969	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		323	
	non noble metal	copper	7440-50-8	3.000	32.18	32.32	321774	323131
wire	non noble metal	copper	7440-50-8	0.008	0.08	0.08	832	832
encapsulation	organic material	carbon black	1333-86-4	0.058	0.62		6187	
	plastics	epoxy resin	-	1.240	13.30		133012	
	inorganic material	silicondioxide	60676-86-0	4.471	47.95	61.87	479461	618660
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16048	16048
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30502	30502
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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